

# News Release

**FOR IMMEDIATE RELEASE**

## **Elpida Memory Issues 6th Unsecured Straight Bonds**

**TOKYO, JAPAN, November 22, 2007** – Elpida Memory, Inc. (Elpida), Japan’s leading global supplier of Dynamic Random Access Memory (DRAM), today announced that it has determined the terms of the 6th unsecured straight bonds (with inter-bond *pari passu* clause) based on the domestic straight bond shelf registration (registered amount: JPY150 billion, effective period: through October 26, 2009) as stated below.

### **Description of Bonds**

#### **Elpida Memory, Inc. 6th Unsecured Straight Bonds (with inter-bond *pari passu* clause)**

- Issue Size: JPY 20 billion
- Denomination: JPY 100 million
- Interest Rate: 2.10 % per annum
- Issue price: JPY100 per face value JPY 100
- Duration: 5 years
- Maturity Date: November 29, 2012
- Interest Payment Date: May 29, and November 29 each year
- Payment Date: November 29, 2007
- Underwriters: Nomura Securities Co., Ltd. and Mizuho Securities Co., Ltd. (joint lead managers and joint bookrunners)
- Fiscal Agent: Mizuho Corporate Bank, Ltd.
- Rating: BBB+ (Japan Credit Rating Agency, Ltd.)
- Use of Proceeds: Repayment of loans and lease obligations

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**About Elpida Memory, Inc.**

Elpida Memory, Inc., (Tokyo Stock Exchange: Code 6665), is a leading global manufacturer of Dynamic Random Access Memory (DRAM) silicon chips. Our design, manufacturing, and sales operations are backed by our world-class technology expertise. Our manufacturing facilities, Hiroshima Elpida Memory, Inc. (wafer processing) and Akita Elpida Memory, Inc. (packaging and testing), utilize the most advanced manufacturing technologies available in the industry. Elpida's portfolio of advanced products features such characteristics as high-density, high-speed, low power and small packing profiles. The company provides applications across a wide range of areas, including high-end servers, mobile phones and digital consumer electronics. For more information about Elpida, please visit <http://www.elpida.com>.

*This is a press release document intended for publicizing the issuance of the corporate bonds and is not intended for solicitation of the bonds.*

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